

Message From the Incoming Editor-in-Chief

OUR TRANSACTIONS are gaining popularity among authors. In 2004, we received approximately 400 manuscripts, and in 2006, we received over 1000 manuscripts. The large number of paper submissions and a significantly shorter review time (due to the electronic process) resulted in a larger number of accepted papers awaiting publication. In order to eliminate the backlog of papers, the IEEE Industrial Electronics Society Administrative Committee at its November meeting in Paris, France, allocated significant financial resources that would almost double the number of printed pages in 2007. We hope that by the end of 2007, we will be able to eliminate this backlog. As a parallel measure, we will try to publish papers on IEEE Xplore well ahead of the scheduled publication date.

It appears that this increased interest in industrial electronics seems to be a general trend because the number of submitted papers to our major conferences (IECON, ISIE, ICIT, INDIN, ETFA, and ICM) has doubled in the last two years. In 2004, 1928 papers were submitted to our major conferences, and in 2006, for the same conferences, we received 4096 papers. It is worth noting that each of our conferences requires full paper submissions for evaluation and three independent reviews are conducted on each paper. The acceptance rate in our conferences is 55%–70%. The review process for the IEEE TRANSACTIONS ON INDUSTRIAL ELECTRONICS (TIE) is more rigorous than for conferences. It is done by a team of about 50 Associate Editors and approximately 1400 Reviewers; without their tremendous effort it would not be possible to run the TRANSACTIONS.

In 2007, we will try to further improve our editorial process with the following modifications.

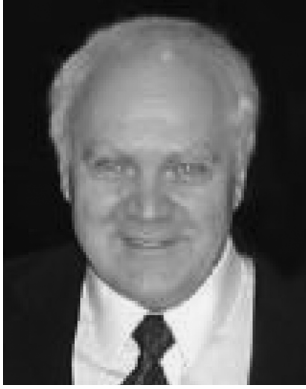
- 1) It is our goal to further shorten the review process so that the majority of authors will be able to receive feedback and the editorial decision within 90 days from the submission date.
- 2) We will change the manuscript submission format to the standard two-column IEEE format, as this is already being done at all our conferences. The special format will be needed only for the final versions of the accepted manuscripts.
- 3) The review process will be carried out without the authors' names and their affiliations; therefore, we will ask authors

to submit manuscripts without authors' names. Authors' names will only be in the electronic system and they will not be visible to reviewers.

- 4) Another change is a switch from Manuscript Central version 1.8 to a newer and better version 3.2.
- 5) We are also introducing a new format of short papers for rapid publication of most current technical accomplishments. These papers, 3–4 pages in length, will be processed by an expedited review process where major manuscript revision will not be an option.
- 6) All accepted papers will be published on IEEE Xplore as soon as they are ready, even though the printed version could be published with a delay (due to the page limit).
- 7) We will try to keep papers within the scope of the TIE. Papers out of this scope will be returned to authors with suggestions of its submission to other journals. Please note that sometimes it is difficult to objectively define the scope of a manuscript. One relatively objective measure of verifying the association of a submitted manuscript with the TIE would be to examine if the manuscript references their findings to previously published papers in the TIE.
- 8) We will not accept papers which have already been published elsewhere (conference or journal). We may, however, accept enhanced versions of conference papers with 40%–50% of new content. Such papers have to include the original conference papers as references and may have a slightly different title.
- 9) We will make an effort to recognize authors with the most citations and also the most frequently read papers.

During the last three years, our editorial process has gone through significant transformations from a fully paper-based submission and review process to a partially electronic and partially paper-based process to a fully electronic process. I would like to thank Prof. Marian P. Kazmierkowski and his team for managing this TRANSACTIONS during this difficult time. I would also like to take this opportunity to thank the large number of Reviewers and Associate Editors for their hard work.

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Bogdan M. Wilamowski (SM'83–F'00) received the M.S. degree in computer engineering, the Ph.D. degree in neural computing, and the Dr. Habil. degree in integrated circuit design from the Technical University of Gdansk, Gdansk, Poland, in 1966, 1970, and 1977, respectively.

He received the title of Full Professor from the President of Poland in 1987. He was the Director of the Institute of Electronics (1979–1981) and the Chair of the Solid State Electronics Department, Technical University of Gdansk, Poland (1987–1989). He was a Professor at the University of Wyoming (1989–2000). From 2000 to 2003, he was Associate Director of the Microelectronics Research and Telecommunication Institute, University of Idaho, and was a Professor in the Department of Electrical and Computer Engineering and the Department of Computer Science, University of Idaho. Currently, he is the Director of the Alabama Micro/Nano Science and Technology Center (AMNSTC) and a Professor in the Department of Electrical and Computer Engineering, Auburn University, Auburn, AL. He was with the Communication Institute, Tohoku University, Japan (1968–1970), and he spent one year at the Semiconductor

Research Institute, Sendai, Japan, as a JSPS Fellow (1975–1976). He was a Visiting Scholar at Auburn University (1981–1982 and 1995–1996), and a Visiting Professor at the University of Arizona, Tucson (1982–1984). He is the author of four textbooks, approximately 300 refereed publications, and 27 patents. He was the major professor for about 120 graduate students. His main areas of interest are electronics and instrumentation, computational intelligence, CAD development, solid-state electronics, mixed-signal, and analog signal processing.

Prof. Wilamowski was the Vice President of the IEEE Neural Network Council/Society (2000–2003), Vice President of the IEEE Computational Intelligence Society (2003–2004), and the President of the IEEE Industrial Electronics Society (2004–2005). He served as an Associate Editor of the IEEE TRANSACTIONS ON NEURAL NETWORKS, IEEE TRANSACTIONS ON EDUCATION, IEEE TRANSACTIONS ON INDUSTRIAL ELECTRONICS, *Journal of Intelligent and Fuzzy Systems*, *Journal of Computing*, *International Journal of Circuit Systems*, and *IES Newsletter*. He is currently the Editor-in-Chief of the IEEE TRANSACTIONS ON INDUSTRIAL ELECTRONICS.